PCN Number:	20181022002.0	**PCN Date:**	October 24, 2018
Title:	Datasheet for TMP112		
Customer Contact:	PCN Manager	**Dept:**	Quality Services

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.
The product datasheet(s) is being updated as summarized below.
The following change history provides further details.

TEXAS INSTRUMENTS

TMP112

SBOS473H – MARCH 2009 – REVISED OCTOBER 2018

Changes from Revision G (May 2018) to Revision H — **Page**

- Added content to the ADD0 pin description in the *Pin Functions* table 3
- Changed the supply voltage maximum value in the *Absolute Maximum Ratings* table from: 5 V to: 4 V 4
- Changed input voltage maximum value for the SCL, ADD0, and SDA pins in the *Absolute Maximum Ratings* table from: 5 V to: 4 V 4
- Changed input voltage maximum value for the ALERT pin in the *Absolute Maximum Ratings* table from: (V+) + 0.5 V to: ((V+) + 0.5) and ≤ 4 V 4
- Changed Junction-to-ambient thermal resistance from 200 °C/W to 210.3 °C/W 4
- Changed Junction-to-case (top) thermal resistance from 73.7 °C/W to 105.0 °C/W 4
- Changed Junction-to-board thermal resistance from 34.4 °C/W to 87.5 °C/W 4
- Changed Junction-to-top characterization parameter from 3.1 °C/W to 6.1 °C/W 4
- Changed Junction-to-board characterization parameter from 34.2 °C/W to 87.0 °C/W 4

The datasheet number will be changing.

Device Family	Change From:	Change To:
TMP112	SBOS473G	SBOS473H

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/TMP112

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

TMP112AIDRLR	TMP112AIDRLT	TMP112BIDRLR	TMP112BIDRLT
TMP112NAIDRLR	TMP112NAIDRLT		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com